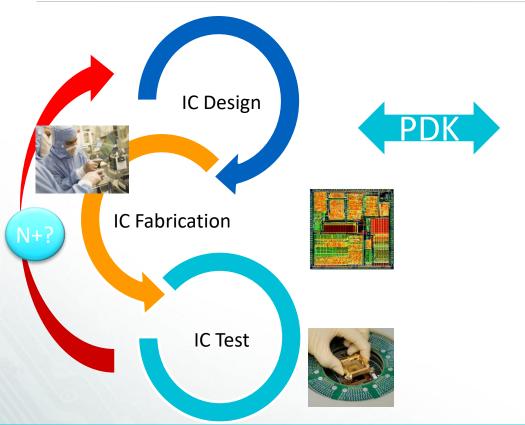


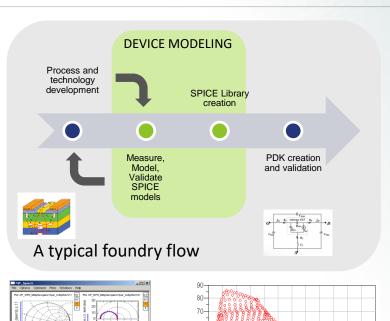
Autonomous RF Measurement assistant

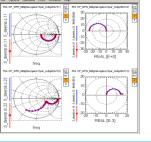
Toru Sugawara – Applications Engineer

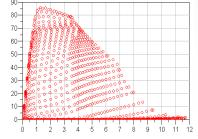


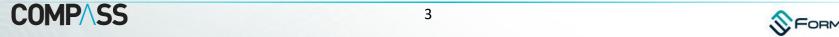
Why is Device Modeling Critical



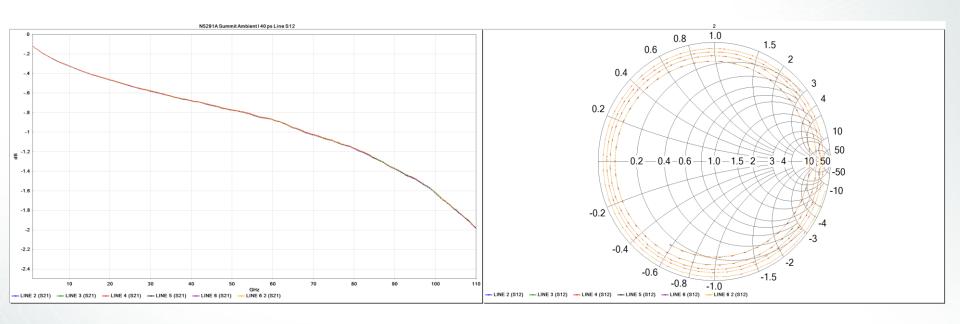








Goal – Accurate Data



More Accurate Data = Better PDK = Faster Time to Market = \$\$\$



Pain Points – Testing over Temperature

Measurements at ambient can be challenging, but measuring over temperature is much harder

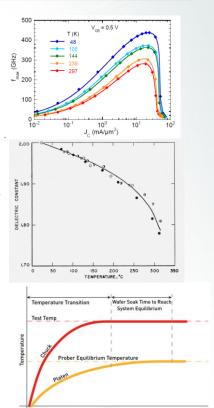
Device modelling for Process Design Kits requires testing from -40degC to +125degC

Calibration more prone to drift due to expansion of probes and cables

Probe to pad alignment errors due to expansion of chuck, wafer, platen, positioners, probes and more

Problems have become more significant with shrinking pad dimensions

RF Pads typically as small at 50x50um







Mechanical effects of growth

Probes grow / retract with temperature in XZ

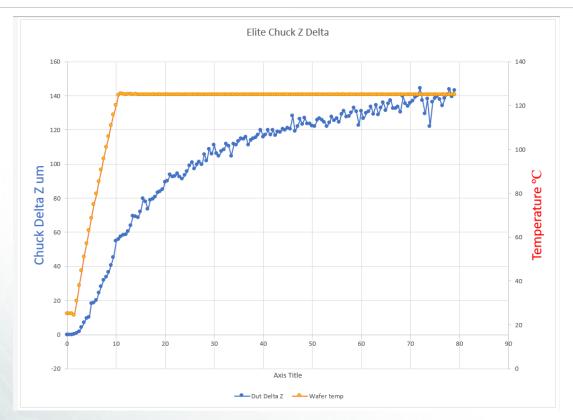
Some movement in Y but comparatively minimal

For significant thermal changes evaluate theta also

Chuck grows in XYZ



Chuck Z expansion

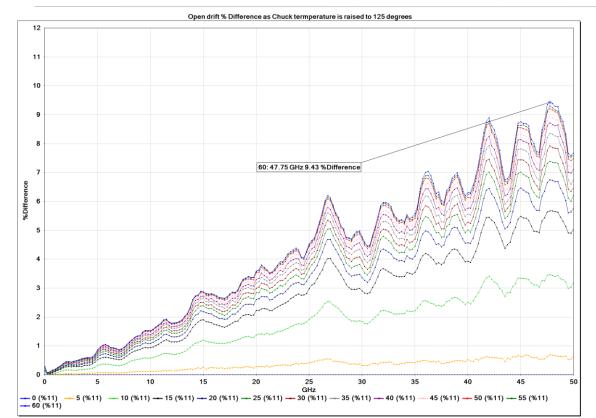


Chuck to probe geometry change during soak

Ideally we would like to probe during growth to save time



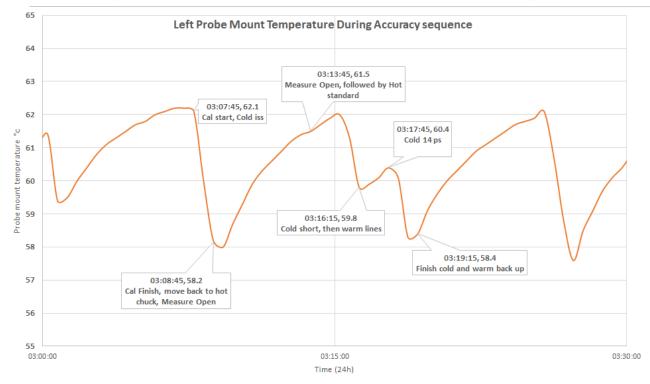
S parameter change during probe warm up



- This was a 50 GHz example
- Reference set at ambient
- System was calibrated and probes left above chuck
- Chuck temperature raised to 125 degrees
- This is the Vector delta * 100 change during warm up without contact to the chuck
- Because of these changes we need to calibrate at operating temperature



Temperature variation during calibration

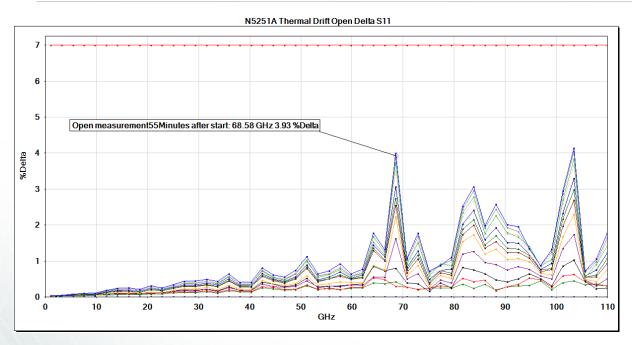


----- Probe Mount

- Graph shows the change in temperature of probe base during 1.5 minute calibration cycle
- Manually positioning probes on ambient ISS can be inaccurate and time consuming



Problem – Calibration Drift



- Calibration drifts with time and temperature changes
- Magnitude increases with frequency
- Transitioning chuck temperature invalidates calibration
- Drift has been greatly improved using N5291A system but still a consideration





Pain Points – Calibration Drift

Even a good calibration will drift with time, temperature changes and movement of cables

Even small temperature changes in the room, can cause higher frequency calibrations to drift

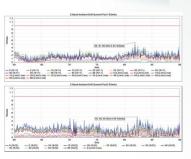
There is no automation of monitoring the magnitude of drift error

Manual checks can be made of the open standard at any time, but automating this requires programming in the test executive

And no autonomous way to re-calibrate once the drift has exceeded a limit

If the calibration is found to be no longer valid, then the user needs to stop the testing and perform the whole calibration again

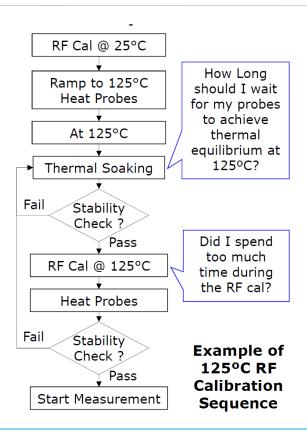








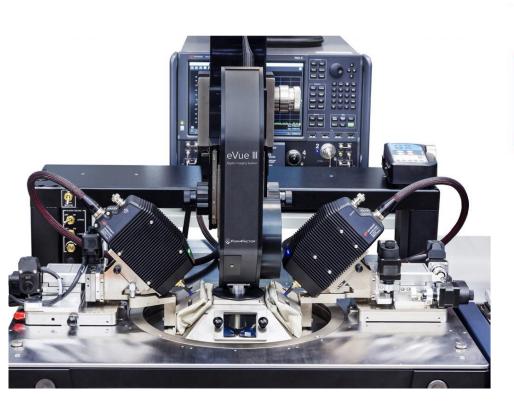
Over temperature calibration general approach



- Doing all of this takes skill, patience and experience
- Doing things without the checks can result in erroneous data
- Getting calibration fast enough is very tricky even for experienced users and compromises are often made
- Machine must be "nursed"



Introducing – Autonomous RF Measurement Assistant



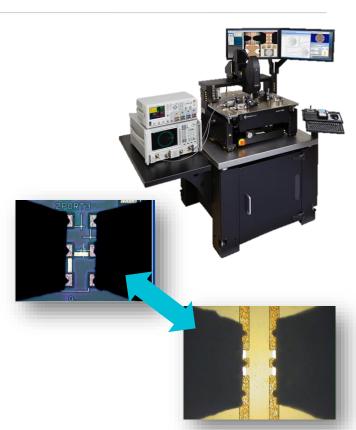


"Only the Autonomous RF
Measurement Assistant, a
combination of programmable
positioners, a precise digital
microscopy system and advanced
pattern recognition algorithms,
enables fully autonomous, hands-free
calibrations and measurements of RF
devices over multiple temperatures."



Autonomous RF

- True Automatic, hands free calibration
- Setup of Calibration requires no expert placement, all automatic
- Monitors calibration drift, re-calibrates automatically
- Full management of system expansion and RF stability
- Full thermal automatic calibration
- Save time & increase data accuracy
- Corrects "thermally induced" probe electrical errors

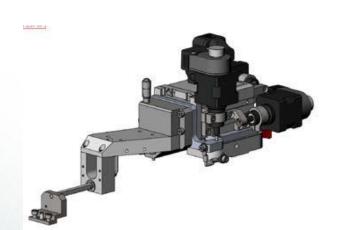


Compact High resolution Programmable Positioner



- Compact positioner allows for multiple motorised positioners on the same prober
- Designed from the ground up for best accuracy, repeatability and service life

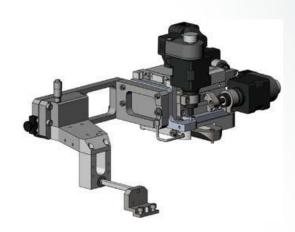
New RPP504 Programmable Positioners



RPP504-EW-67



RPP504-EW-120



RPP504-NS-67





Reduced path length and improved performance



- Tophat designed to minimise cable lengths and prevent stiction which impacts motorised positioner accuracy
- Reducing cable length helps to improve system drift and dynamic range
- Autonomous RF currently limited to max 130 GHz and Infinity probes
- Can be used with conventional sub 67 GHz coaxial probes





System Photos – Probe Window



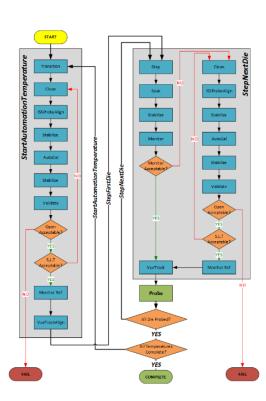
- Clear window designed to ease setup when south positioner is not in use
- Quickly sealable using metal cover
- Shielded to prevent charge build up



Integrating Automation assistant into test executive

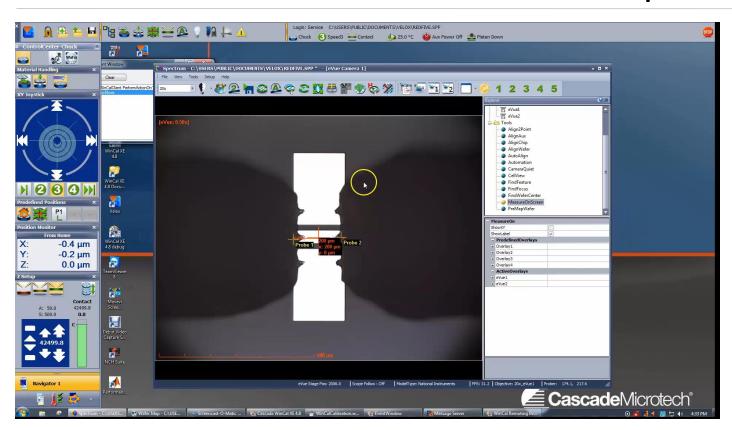
StartAutomationTemperature X does all this...

- Changes temperature and maintains probe to probe, and probe to wafer geometry at Separate
- Die soak at end of transition at align height always maintaining geometry
- Checks using VNA to test for electrical stability
- Moves bias probes out of field of view
- Aligns probes at ISS using defined spacings
- Re-checks stability to ensure probes didn't cool down
- Calibrates system
- Verifies
- Takes monitoring data to check system is stable later on
- Returns probes to wafer Geometry ready for test
- Addition options of this command performs Theta align and sizing





Autonomous RF Measurement Setup video



Video



Scripting in Python

This code is enough to measure all die on a wafer at 3 different temperatures using WinCal

Red Ringed are automation activities



Multiple device layouts

- Autonomous RF supports different probe spacings for automatic movement to different device topologies
- Setup using script commands
- Scripting examples supplied to use the wafermap label to dynamically set a probe spacing for a given Subdie





| UseScrubMarkAlign | |
|--------------------|------------|
| | |
| ■ VueTrackFeatures | |
| ■ ProbeLayouts | |
| LayoutCount | 2 |
| | |
| ☐ layout2 | |
| LayoutName | GoodLayout |
| ProbeCount | 3 |
| ☐ probe1 | |
| ProbeID | 3 |
| ■ XYOffset | 1.00, 2.00 |
| ☐ probe2 | |
| ProbeID | 4 |
| ■ XYOffset | 2.00, 3.00 |
| ☐ probe3 | |
| | |



Using with Robotic loader on Summit 200 or CM300

```
Scripting Console
File Edit Commands Run/Debug Options Help
                 📭 🦒 😂 💺 🐽
                 script with wafer loading added.py
DieStepper(total subdie, count, wafer)
         #Main function where the die stepping is done and measurements
     48 ⊡def DieStepper(total subdie,count,wafer):
              print("Wafer is " + wafer)
              totaldie = GetNumSelectedDies()
              print("Total die =" + str(totaldie))
     52
              MoveAuxSite(0)
     53
              #Aligns the wafer
              print("aligning the wafer")
            VueTrackAlign(1)
              MoveChuckSeparation()
              #MoveTheta(0, "H")
     59
              #MoveChuck(0,0,"H")
              #removed the step to die 2 - maybe not needed
     61
     62
              for die number in range (1,totaldie+1,1):
     63
                  print("Moving to die#" + str(die number))
                  MoveChuckSeparation()
                  StepToDie(die number)
                  for site_number in range (0,total_sub_die,1):
                     sep = ReadChuckHeights()[3]
                     print("Moving to subsite#" + str(site number))
     71
                     MoveChuckSeparation()
                     StepNextSubDie (site number)
                     label= GetSubDieLabel() #Unpack tuple with the ,
     73
                     print("Moving to stored position called " + label)
                     MoveToAutomationProbeLayout(label)
                     MoveChuckContact()
                     MoveEvueFocusStage(focus start)
```



■Sample scripts available to show multi wafer, multi die, multi site automatic over temperature automation



Autonomous RF Key Value Propositions

Ease of use – An inexperienced operator can perform an RF calibration up to 130 GHz by simply pushing a button. This reduces the need of the experienced users full time on each system

Reduced Soak Time – System will re-align the probes to the pads if they drift away from alignment. This reduces the time of test and increases throughput

Unattended Use – Measurements can be left running over night, testing all devices on the wafer, and at different temperatures without the need of the operator.

Calibration Monitor and Re-calibration – System will continuously monitor calibration drift, and automatically re-calibrate the system should the drift exceed a pre-defined limit

Data volume – unattended test allows more tool utilisation without additional time and money

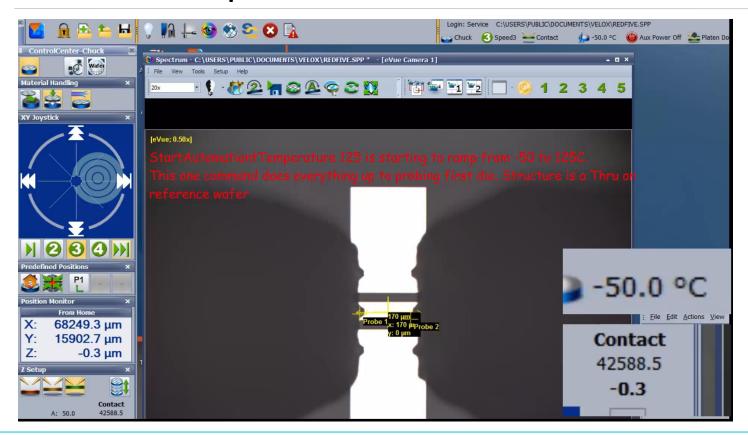
Faster Time to Data

Lower Costs of Testing





Video –Temperature transition Run -50C to 125C



Video



Thank You!

For questions, please contact:

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